

SECTION A-A

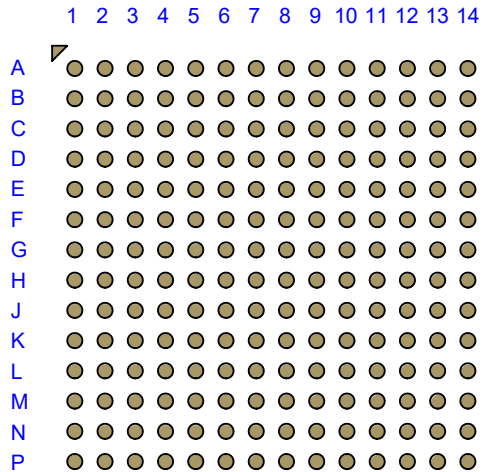
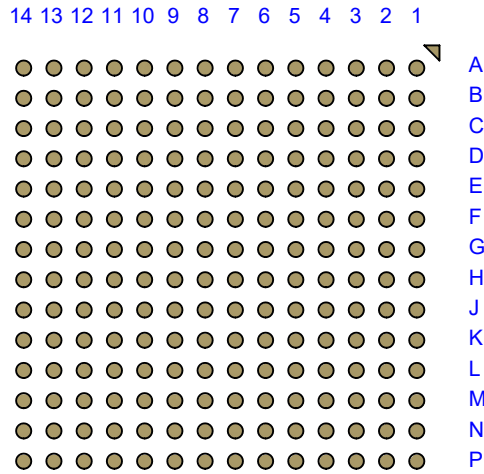
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS: MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm (14 MIL).
- 5) PAD Cu DIAMETER: 0.508mm (20 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE					
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE	DAISY
BGA196T1.0-D-GT	Sn63/Pb37	NO	NO	YES	NO

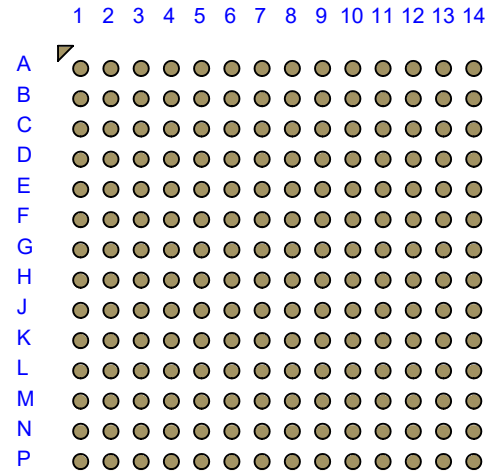
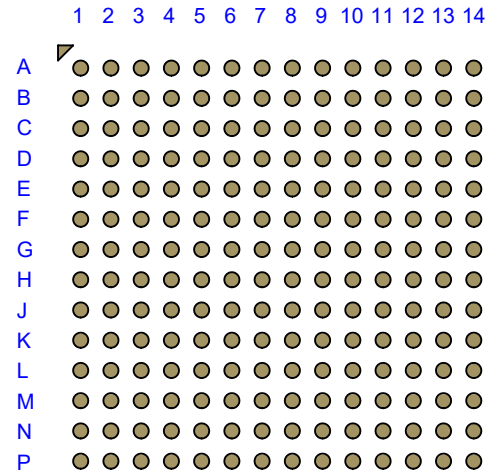
APPROVALS	DATE	TopLine®			
DRAWN T.Au	04/24/2024				
ENG M. Hart	04/24/2024	TITLE BGA196T1.0-D-GT DUMMY PBGA			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	511401	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

BALL VIEW



TEST VEHICLE BOARD

BOTTOM SIDE (TOP X-RAY VIEW)



AFTER MOUNTING

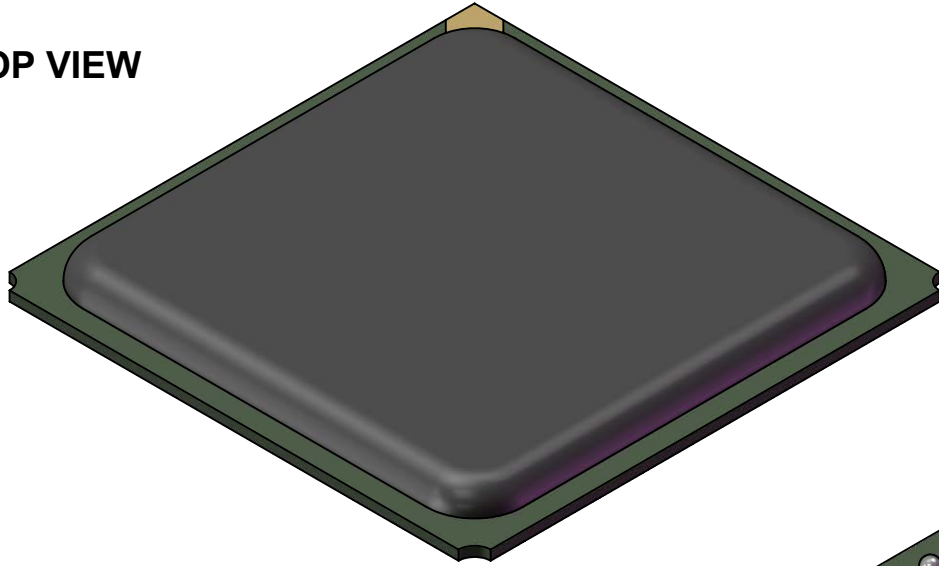
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.508mm (20 MIL).
- 3) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.36mm (14 MIL).

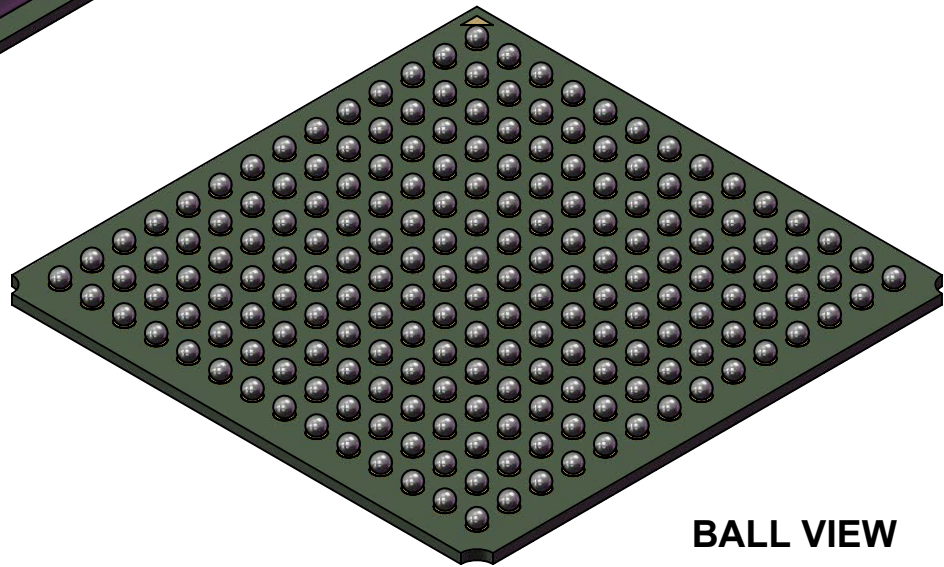
TopLine®			
TITLE		BGA196T1.0-D-GT DUMMY PBGA	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	511401	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP VIEW



BALL VIEW



TopLine[®]

TITLE BGA196T1.0-D-GT
DUMMY PBGA

SCALE 6:1	SIZE A	DRAWING NO. 511401	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3